



MIXED SIGNAL RADIATION TOLERANT DESIGN WITH DARE



OVERVIEW

- ▶ Mixed Signal ASIC Design Flow
- ▶ Design Analog Blocks
- ▶ Integration of Analog Blocks
- ▶ DARE ASICs
 - LEONDARE
 - KNUT
 - SSOC
- ▶ Conclusions

*Design
Against
Radiation
Effects*

*DARE180
DARE+
(DARE90)*

MIXED SIGNAL DESIGN FLOW

▶ Digital-on-top approach vs Analog-on-top depends on:

- Complexity of digital part
- Interface (# signals, timing) digital-analog
- Area estimation digital/analog
- Number/type of analog blocks
- Experience/familiarity with digital/analog flow

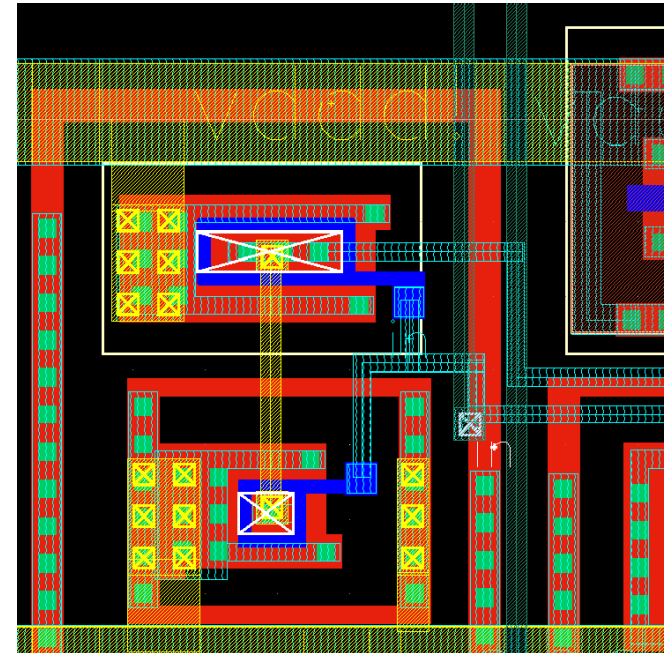
⇒ digital-on-top preferred for DARE

▶ Extra requirements for analog blocks

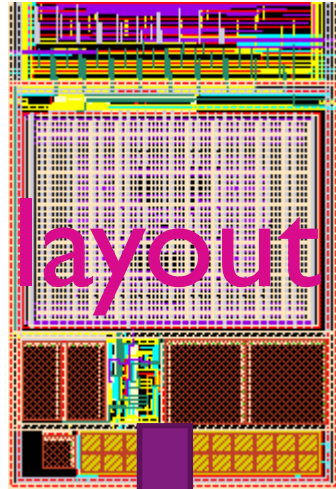
- Floor planning, placement and routing
 - Additional layers, additional labels, port placement, ..
- Timing analysis
 - Additional simulations

DESIGN ANALOG BLOCKS

- ▶ Schematic entry + SPICE simulation
- ▶ Standard available UMC Mixed-Mode PDK (IC6.1)
 - ⇒ Analog Design Kit enhancement for ELT and TID (DARE+)
- ▶ Standard DRC checking
- ▶ Custom LVS checking
- ▶ Extra RAD checking
 - ⇒ NMOS ELT compliance
 - ⇒ Presence of guard bands
 - ⇒ Forbidden polysilicon routing



INTEGRATION OF ANALOG BLOCKS

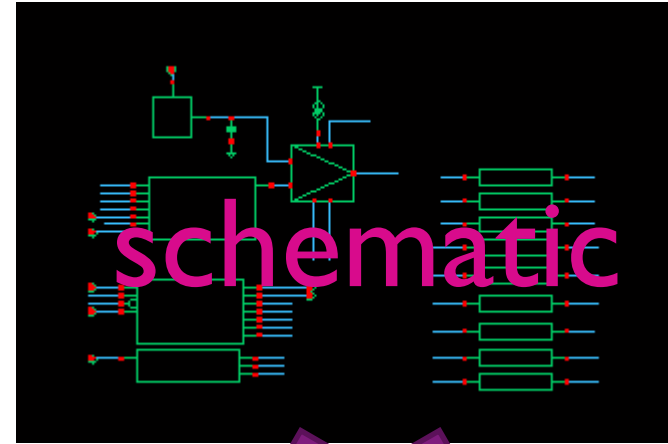


layout



abstract generator
LEF script

LEF file



schematic



analog simulation
LIB template

LIB file

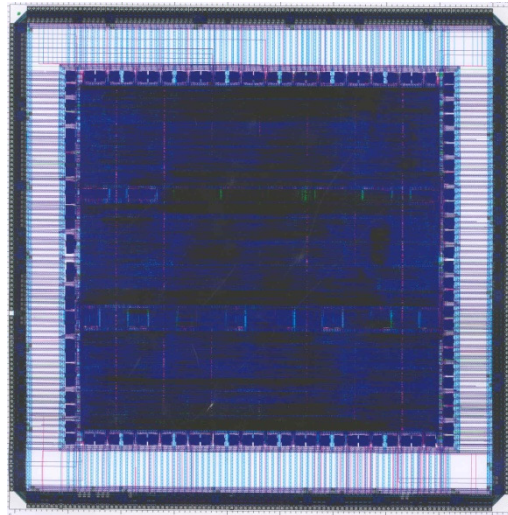


model description

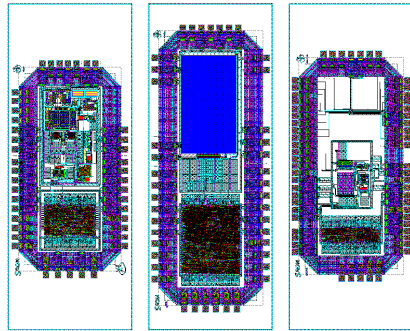
vhdl

DARE ASICS: ESA PROJECTS

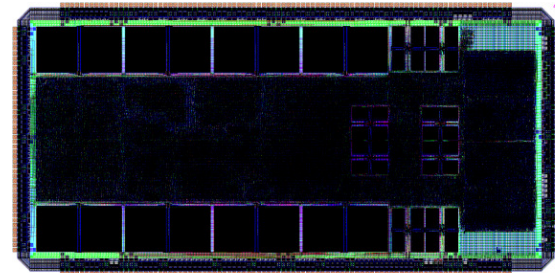
DROM



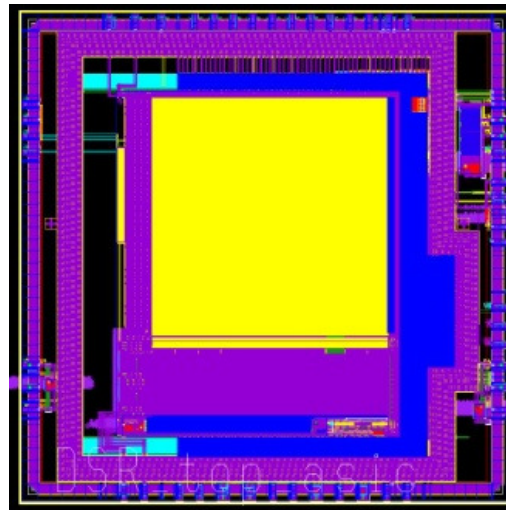
First functional DARE silicon



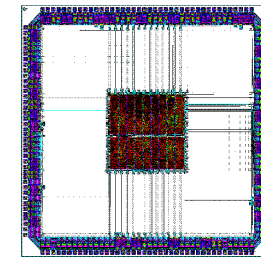
LEONDARE



SSOC



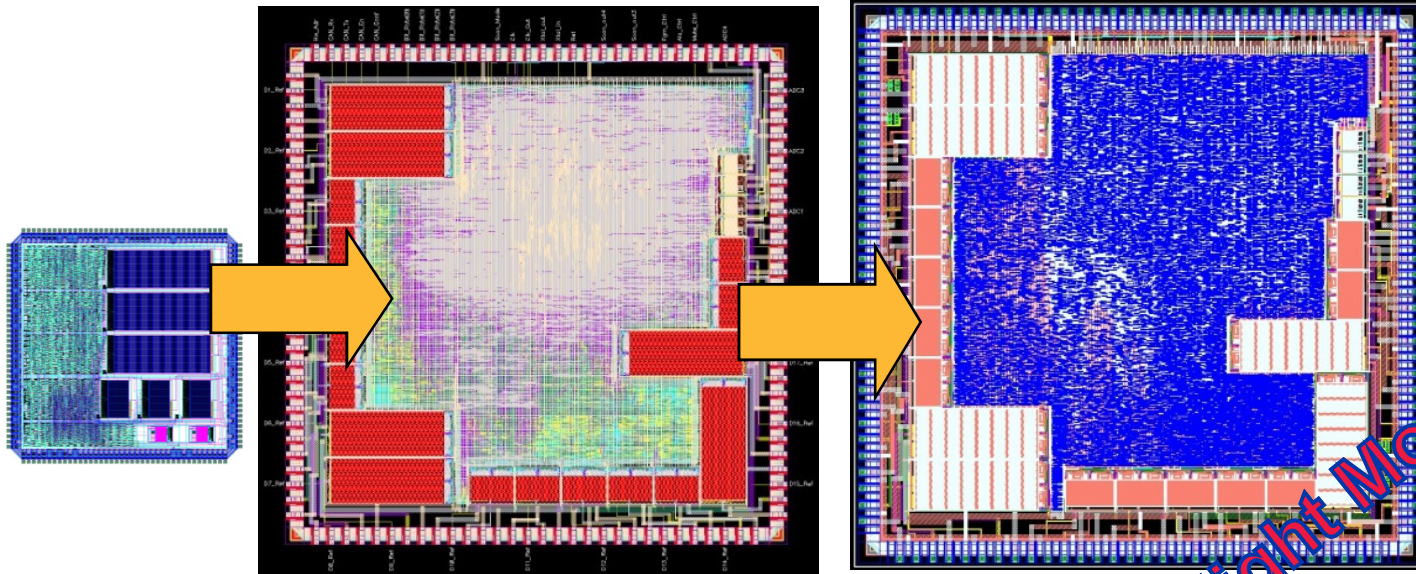
CIS Port



RUAG

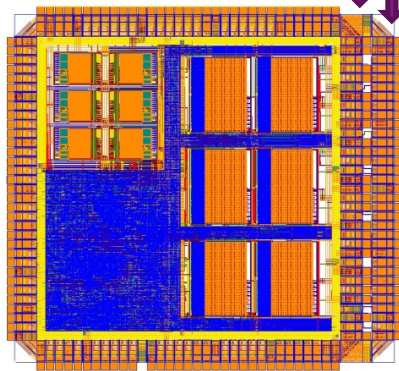
Muller-C gate added

DARE ASICS: CUSTOMER CHIPS



Flight Models

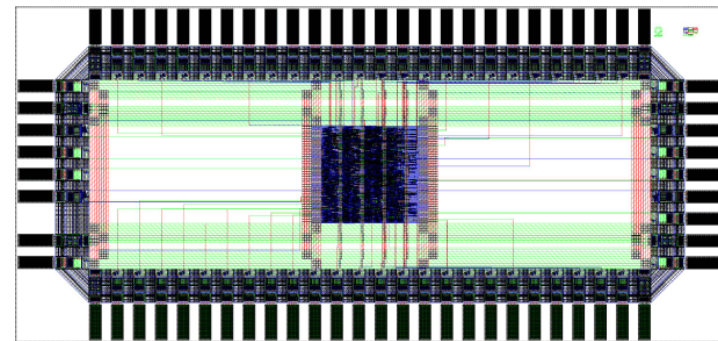
Dual bond



(Slow)
ADC & DAC
IP blocks

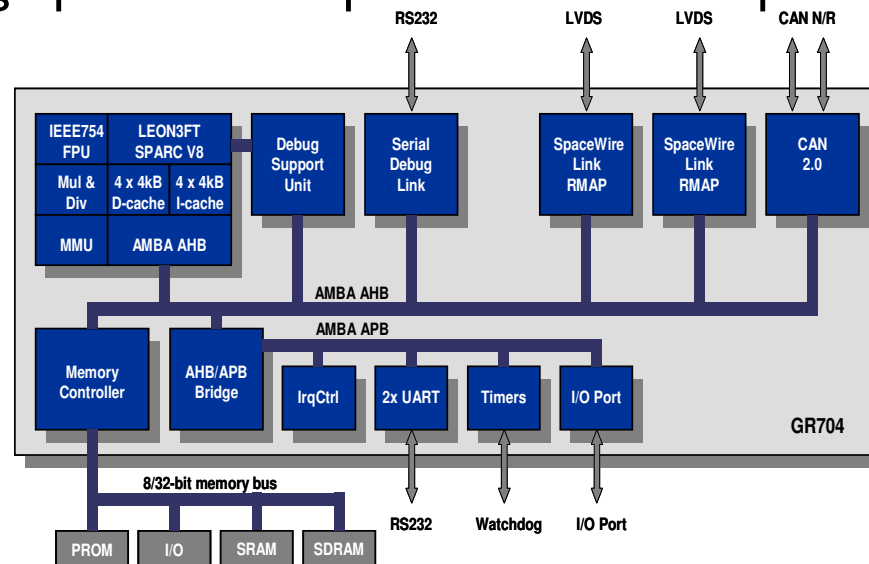


ARQUIMEA



LEONDARE ASIC

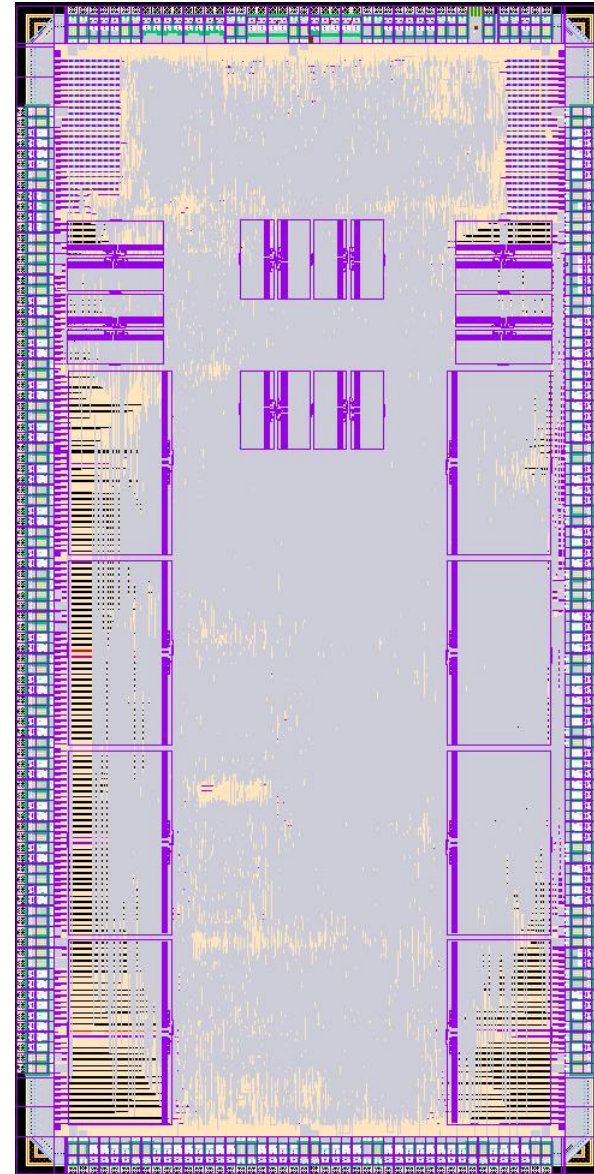
- ▶ Evaluate the technology according to a dedicated production and evaluation flow complying with the ESCC standards
- ▶ Aeroflex-Gaisler LEON3-FT IP + IP Peripherals
 - Appropriate complexity for evaluating a technology (SRAM, PLL, LVDS,...)
 - High-performance processor for the space domain



LEONDARE

- ▶ 120 MHz
- ▶ PLL
- ▶ LVDS
- ▶ SRAM

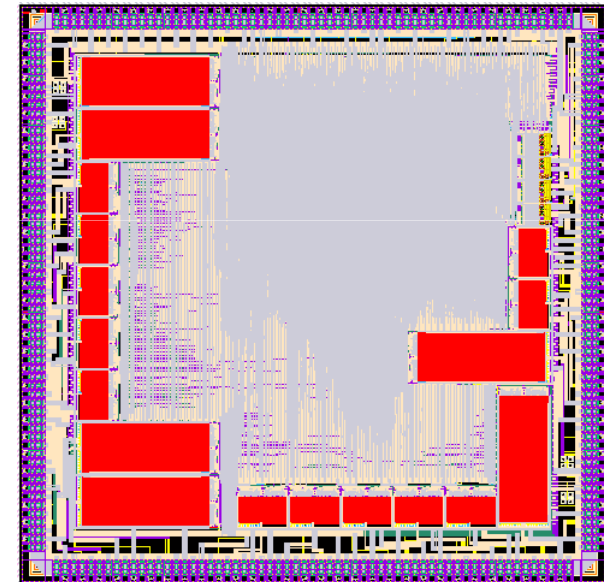
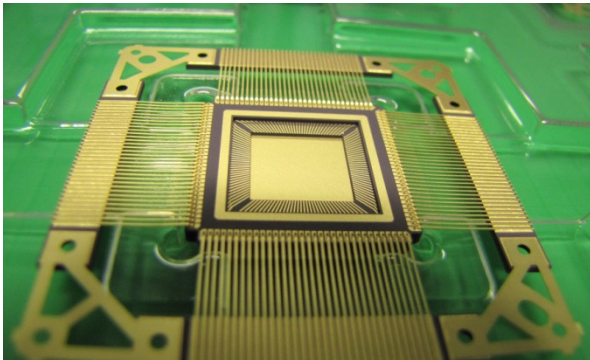
- ▶ CQFP256 (custom)
- ▶ Evaluation & Qualification



KNUT ASIC

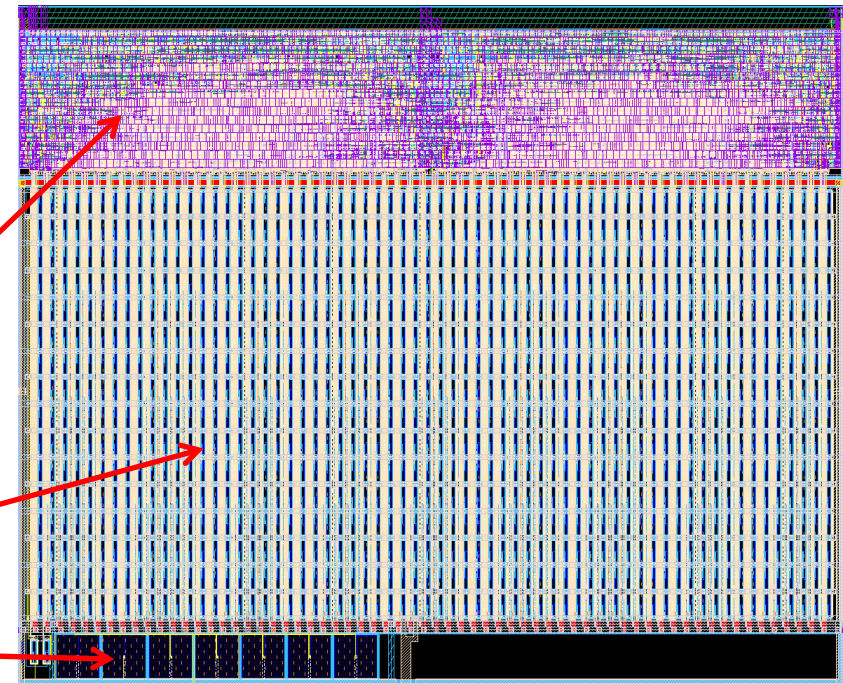
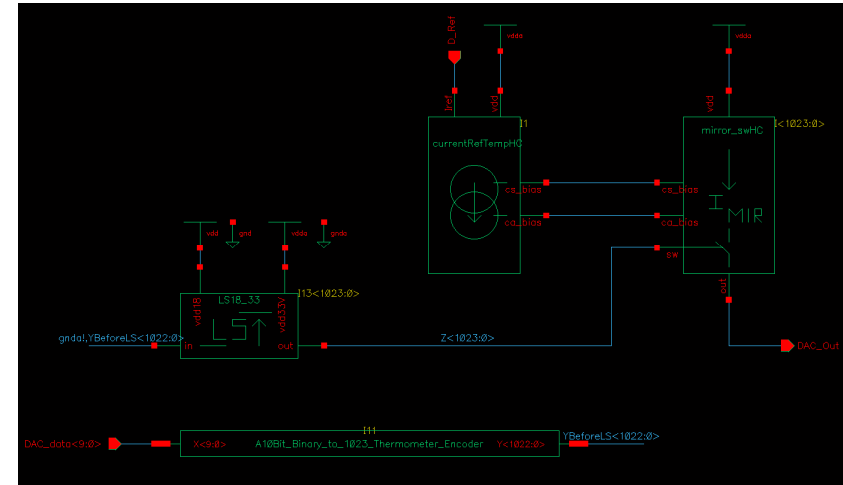
- ▶ TESAT Spacecom GmbH & Co.KG
- ▶ UMC 180nm IP6M + MiM
- ▶ Mixed Signal ASIC
 - 88 mm²
 - 120 I/O
 - Digital core
 - Analog blocks

300K gates
ADC (4)
DAC (18)
I/O (88)



10 BIT DAC

Specification	Range
Resolution	10 bit
DNL	< 1 LSB
INL	< 1 LSB
Temperature Range	-55 °C .. +125 °C
Analog Supply Voltage	VDDA = 3.3 V +/- 10%
Temperature Drift	< 10 LSB
ILSB low current range	1 μ A .. 6 μ A
ILSB high current range	5 μ A .. 30 μ A
Total Dose	100 krad



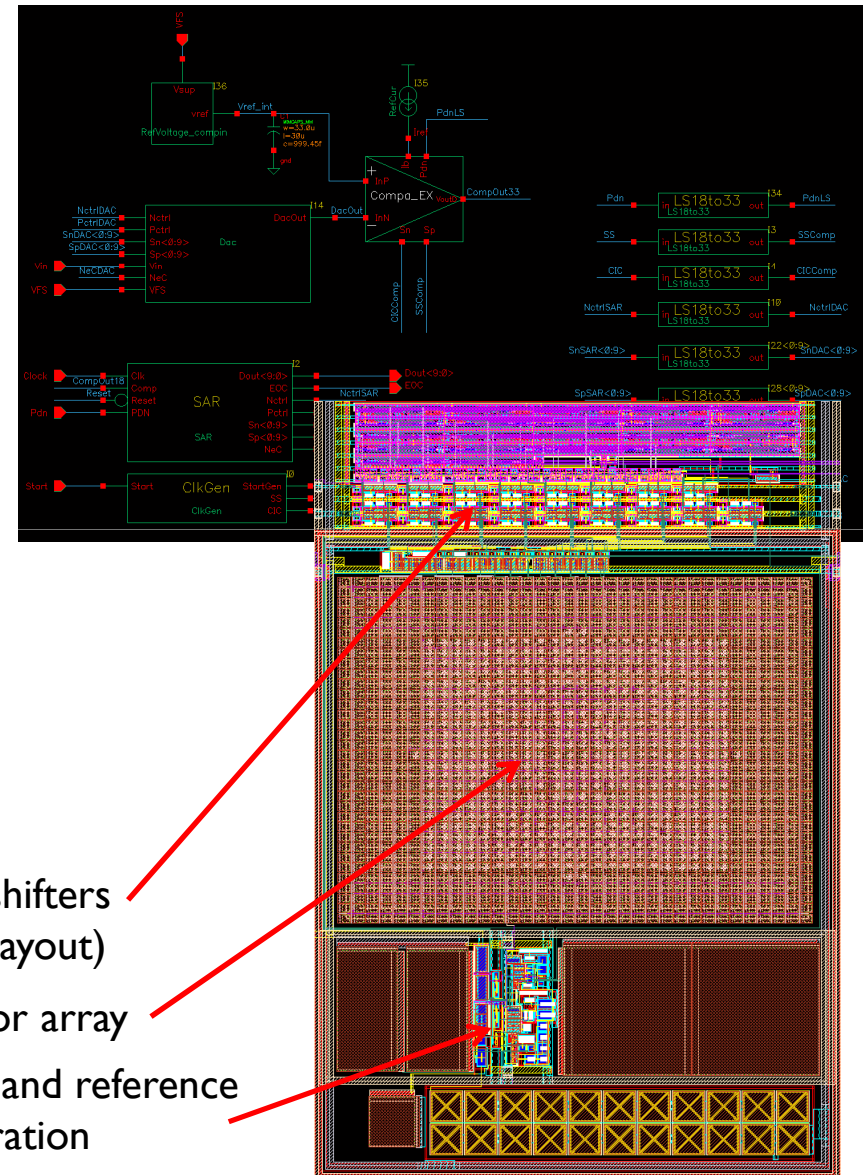
10b Bin2Thermo
(fully digital P&R)

Current sources with
local level shifter

Bias voltage generation

10 BIT ADC

Specification	Range
Resolution	10 bit
DNL	$< 1 \text{ LSB}$
INL	$< 1 \text{ LSB}$
Temperature Range	$-55 \text{ }^\circ\text{C} \text{ .. } +125 \text{ }^\circ\text{C}$
Analog Supply Voltage	$VDDA = 3.3 \text{ V} \pm 10\%$
Temperature Drift	$< 1 \text{ LSB}$
Input Voltage Range	$0 < V_{in} < V_{FS}$
Full Scale Voltage	$1.4 < V_{FS} < VDDA$
Conversion Speed	$< 1 \text{ ms}$
Total Dose	100 krad



SAR + level shifters
(full custom layout)

MiM capacitor array

Comparator and reference
voltage generation

DIGITAL SUN SENSOR ON A CHIP

Application

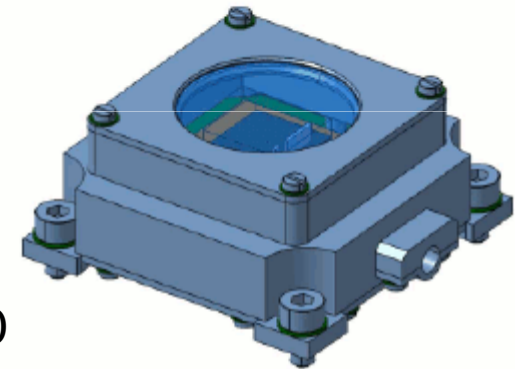


BAE SYSTEMS

- ▶ smart image sensor prototype
- ▶ accurate centroiding of sun image on 2D pixel array for spacecraft altitude determination
- ▶ autonomous, plug and play: light in – coordinates out

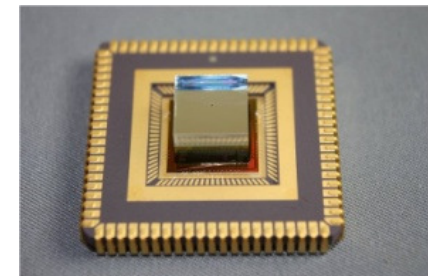
ESA contract 21835/08/NL/ST

- ▶ Selex Galileo (I): prime, unit design and test
- ▶ BAE Systems (UK): immersed MEMS optics
- ▶ CMOSIS (B): sensor chip design and test
- ▶ Kick-off: February 2009 => first silicon: June 2010

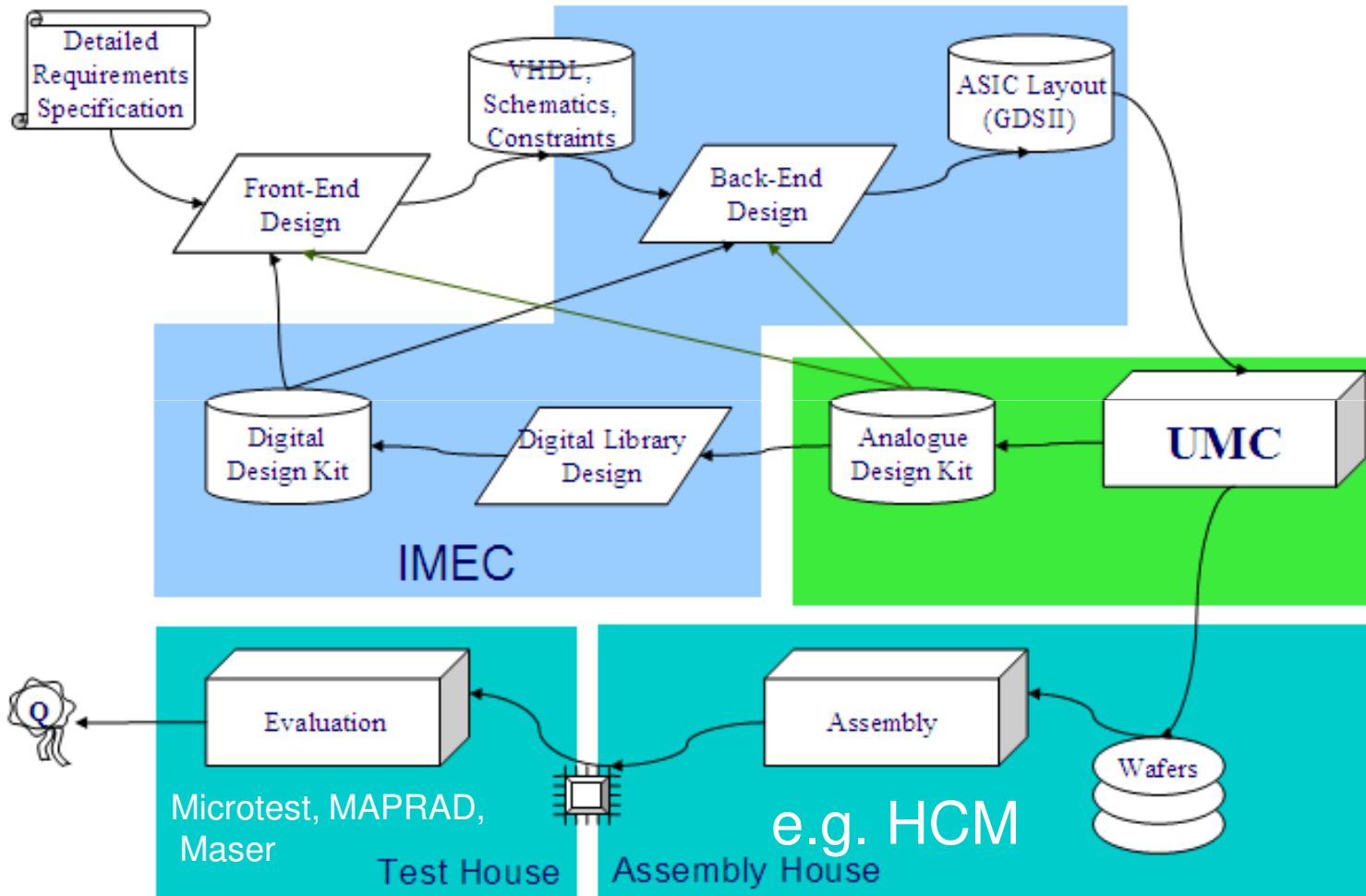


Key requirements: dimensions, cost, robustness, performance

- ▶ radiation (> 300 krad, SEU/SEL-insensitive)
- ▶ ESD
- ▶ supply: 7V peak, low-power (<200mW at 5V)
- ▶ sun detection: no false positives, even in solar storm



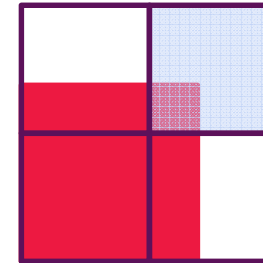
FROM SPECIFICATION TO FLIGHT MODELS



(UMC) PRODUCTION BUSINESS MODEL

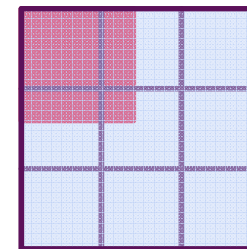
▶ MPW – scheduled runs

- Square of 5x5mm² (1, 2, 4)
- <http://www.europractice-ic.com/docs/MPW2011-general-v7.pdf>
- EUR 16000/square
- 40 dies guaranteed + 30/extra wafer (\pm 1900 EUR/w)
- Dice from WAT accepted wafers only/ no wafers



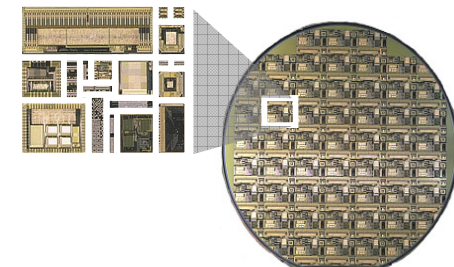
▶ Mini@sic – scheduled runs

- After UMC approval for low cost access
- EUR 2670/square (1525x1525 microns)
- Amount of pins!



▶ Full Mask set – start any time

- \pm EUR 100k – can e.g. hold wafers before metal,...
- Use **ONLY** this for Flight Models



CONCLUSIONS

- ▶ The feasibility of a Mixed Signal design flow for Space Applications with the DARE library is demonstrated for several ASICs
- ▶ The digital-on-top approach is preferred, but needs descriptions of the analog blocks for doing P&R, STA, IR-drop and power analysis
- ▶ RAD check gives added value in mixed-mode designs
- ▶ Analogue Design Kit: ELT and TID modeling upgrade under development



QUESTIONS ?

Design Services: Steven.Redant@imec.be
Full Custom & Library Development: Geert.Thys@imec.be

